

HCPL-4506/J456/0466, HCNW4506

Intelligent Power Module and Gate Drive Interface Optocouplers



Data Sheet

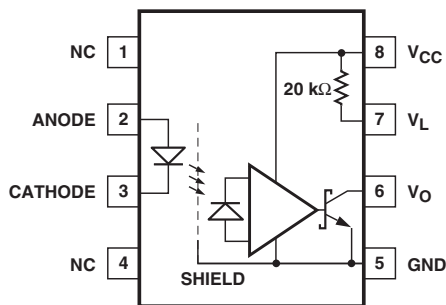


Description

The HCPL-4506 and HCPL-0466 contain a GaAsP LED while the HCPL-J456 and the HCNW4506 contain an AlGaAs LED. The LED is optically coupled to an integrated high gain photo detector. Minimized propagation delay difference between devices makes these optocouplers excellent solutions for improving inverter efficiency through reduced switching dead time.

An on chip 20 kΩ output pull-up resistor can be enabled by shorting output pins 6 and 7, thus eliminating the need for an external pull-up resistor in common IPM applications. Specifications and performance plots are given for typical IPM applications.

Functional Diagram



Truth Table

LED	V _o
ON	L
OFF	H

The connection of a 0.1 μF bypass capacitor between pins 5 and 8 is recommended.

Features

- Performance specified for common IPM applications over industrial temperature range: -40°C to 100°C
- Fast maximum propagation delays
 $t_{PHL} = 480 \text{ ns}$
 $t_{PLH} = 550 \text{ ns}$
- Minimized Pulse Width Distortion
 $PWD = 450 \text{ ns}$
- 15 kV/μs minimum common mode transient immunity at $V_{CM} = 1500 \text{ V}$
- $CTR > 44\%$ at $I_F = 10 \text{ mA}$
- Safety approval:
 UL Recognized
 -3750 V rms / 1 min. for HCPL-4506/0466/J456
 -5000 V rms / 1 min. for HCPL-4506 Option 020 and HCNW4506
- CSA Approved
 IEC/EN/DIN EN 60747-5-2 Approved
 $-V_{IORM} = 560 \text{ Vpeak}$ for HCPL-0466 Option 060
 $-V_{IORM} = 630 \text{ Vpeak}$ for HCPL-4506 Option 060
 $-V_{IORM} = 891 \text{ Vpeak}$ for HCPL-J456
 $-V_{IORM} = 1414 \text{ Vpeak}$ for HCNW4506

Applications

- IPM isolation
- Isolated IGBT/MOSFET gate drive
- AC and brushless DC motor drives
- Industrial inverters

CAUTION: It is advised that normal static precautions be taken in handling and assembly of this component to prevent damage and/or degradation which may be induced by ESD.

Selection Guide

Package Type	Standard 8-Pin DIP (300 Mil)	White Mold 8-Pin DIP (300 Mil)	Small Outline S08	Widebody (400 Mil)	Hermetic*
Part Number	HCPL-4506	HCPL-J456	HCPL-0466	HCNW4506	HCPL-5300 HCPL-5301
IEC/EN/DIN EN 60747-5-2 Approval	$V_{IORM} = 630 \text{ Vpeak}$ (Option 060)	$V_{IORM} = 891 \text{ Vpeak}$	$V_{IORM} = 560 \text{ Vpeak}$ (Option 060)	$V_{IORM} = 1414 \text{ Vpeak}$	—

*Technical data for these products are on separate Avago publications.

Ordering Information

HCPL-0466, HCPL-4506 and HCPL-J456 are UL Recognized with 3750 Vrms for 1 minute per UL1577.
 HCNW4506 is UL Recognized with 5000 Vrms for 1 minute per UL1577. HCPL-0466, HCPL-4506, HCPL-J456 and HCNW4506 are approved under CSA Component Acceptance Notice #5, File CA 88324.

Part Number	Option		Package	Surface Mount	Gull Wing	Tape & Reel	UL 5000 Vrms/ 1 Minute rating	IEC/EN/DIN EN 60747-5-2	Quantity
	RoHS Compliant	non RoHS Compliant							
HCPL-4506	-000E	no option	300 mil DIP-8						50 per tube
	-300E	#300		X	X				50 per tube
	-500E	#500		X	X	X			1000 per reel
	-020E	#020					X		50 per tube
	-320E	#320		X	X		X		50 per tube
	-520E	#520		X	X	X	X		1000 per reel
	-060E	#060						X	50 per tube
	-360E	#360		X	X			X	50 per tube
	-560E	#560		X	X	X		X	1000 per reel
HCPL-J456	-000E	no option	300 mil DIP-8					X	50 per tube
	-300E	#300		X	X			X	50 per tube
	-500E	#500		X	X	X		X	1000 per reel
HCPL-0466	-000E	no option	SO-8	X					100 per tube
	-500E	#500		X		X			1500 per reel
	-060E	#060		X				X	100 per tube
	-560E	#560		X		X		X	1500 per reel
HCNW4506	-000E	no option	400 mil				X	X	42 per tube
	-300E	#300	Widebody	X	X		X	X	42 per tube
	-500E	#500	DIP-8	X	X	X	X	X	750 per reel

To order, choose a part number from the part number column and combine with the desired option from the option column to form an order entry.

Example 1:

HCPL-4506-560E to order product of 300 mil DIP Gull Wing Surface Mount package in Tape and Reel packaging with IEC/EN/DIN EN 60747-5-2 Safety Approval and RoHS compliant.

Example 2:

HCPL-4506 to order product of 300 mil DIP package in Tube packaging and non RoHS compliant.

Option datasheets are available. Contact your Avago sales representative or authorized distributor for information.

Remarks: The notation '#XXX' is used for existing products, while (new) products launched since July 15, 2001 and RoHS compliant will use '-XXE.'

Package Outline Drawings

HCPL-J456 Outline Drawing



DIMENSIONS IN MILLIMETERS AND (INCHES).
 * MARKING CODE LETTER FOR OPTION NUMBERS
 "L" = OPTION 020
 "V" = OPTION 060
 OPTION NUMBERS 300 AND 500 NOT MARKED.

NOTE: FLOATING LEAD PROTRUSION IS 0.5 mm (20 mils) MAX.

HCPL-J456 Gull Wing Surface Mount Option 300 Outline Drawing



DIMENSIONS IN MILLIMETERS (INCHES).
 LEAD COPLANARITY = 0.10 mm (0.004 INCHES).

NOTE: FLOATING LEAD PROTRUSION IS 0.5 mm (20 mils) MAX.

HCPL-0466 Outline Drawing (8-Pin Small Outline Package)



* TOTAL PACKAGE LENGTH (INCLUSIVE OF MOLD FLASH)
5.207 ± 0.254 (0.205 ± 0.010)

DIMENSIONS IN MILLIMETERS (INCHES).
LEAD COPLANARITY = 0.10 mm (0.004 INCHES) MAX.

NOTE: FLOATING LEAD PROTRUSION IS 0.15 mm (6 mils) MAX.

HCNW4506 Outline Drawing (8-Pin Widebody Package)



DIMENSIONS IN MILLIMETERS (INCHES).

NOTE: FLOATING LEAD PROTRUSION IS 0.25 mm (10 mils) MAX.

HCNW4506 Gull Wing Surface Mount Option 300 Outline Drawing



DIMENSIONS IN MILLIMETERS (INCHES).
 LEAD COPLANARITY = 0.10 mm (0.004 INCHES).
 NOTE: FLOATING LEAD PROTRUSION IS 0.25 mm (10 mils) MAX.

Solder Reflow Temperature Profile



NOTE: NON-HALIDE FLUX SHOULD BE USED.

Recommended Pb-Free IR Profile



NOTES:
 THE TIME FROM 25 °C to PEAK TEMPERATURE = 8 MINUTES MAX.
 $T_{smax} = 200\text{ }^{\circ}\text{C}$, $T_{smin} = 150\text{ }^{\circ}\text{C}$

NOTE: NON-HALIDE FLUX SHOULD BE USED.

* RECOMMENDED PEAK TEMPERATURE FOR WIDEBODY 400mils PACKAGE IS 245 °C

Regulatory Information

The devices contained in this data sheet have been approved by the following agencies:

Agency/Standard		HCPL-4506	HCPL-J456	HCPL-0466	HCNW4506
Underwriters Laboratories (UL)	UL 1577 Recognized under UL 1577, Component Recognized Program, Category FPQU2, File E55361	•	•	•	•
Canadian Standards Association (CSA)	Component Acceptance Notice #5 File CA88324	•	•	•	•
Verband Deutscher Elektrotechniker (VDE)	DIN VDE 0884 (June 1992)	•	•		•
IEC/EN/DIN EN 60747-5-2	Approved under: IEC 60747-5-2:1997 + A1:2002 EN 60747-5-2:2001 + A1:2002 DIN EN 60747-5-2 (VDE 0884 Teil 2):2003-01	•	•	•	•

Insulation and Safety Related Specifications

Parameter	Symbol	Value				Units	Conditions
		HCPL-4506	HCPL-J456	HCPL-0466	HCNW4506		
Minimum External Air Gap (External Clearance)	L(101)	7.1	7.4	4.9	9.6	mm	Measured from input terminals to output terminals, shortest distance through air.
Minimum External Tracking (External Creepage)	L(102)	7.4	8.0	4.8	10.0	mm	Measured from input terminals to output terminals, shortest distance path along body.
Minimum Internal Plastic Gap (Internal Clearance)		0.08	0.5	0.08	1.0	mm	Through insulation distance, conductor to conductor, usually the direct distance between the photoemitter and photodetector inside the optocoupler cavity.
Minimum Internal Tracking (Internal Creepage)		NA	NA	NA	4.0	mm	Measured from input terminals to output terminals, along internal cavity.
Tracking Resistance (Comparative Tracing Index)	CTI	≥175	≥175	≥175	≥200	Volts	DIN IEC 112/VDE 0303 Part 1
Isolation Group		IIIa	IIIa	IIIa	IIIa		Material Group (DIN VDE 0110, 1/89, Table 1)

All Avago data sheets report the creepage and clearance inherent to the optocoupler component itself. These dimensions are needed as a starting point for the equipment designer when determining the circuit insulation requirements. However, once mounted on a printed circuit board, minimum creepage and clearance requirements must be met as specified for individual equipment standards. For creepage, the shortest distance path along

the surface of a printed circuit board between the solder fillets of the input and output leads must be considered. There are recommended techniques such as grooves and ribs which may be used on a printed circuit board to achieve desired creepage and clearances. Creepage and clearance distances will also change depending on factors such as pollution degree and insulation level.

IEC/EN/DIN EN 60747-5-2 Insulation Related Characteristics

Description	Symbol	HCPL-0466 Option 060	HCPL-4506 Option 060	HCPL-J456	HCNW4506	Unit
Installation classification per DIN VDE 0110/1.89, Table 1 for rated mains voltage ≤ 150 V rms for rated mains voltage ≤ 300 V rms for rated mains voltage ≤ 450 V rms for rated mains voltage ≤ 600 V rms for rated mains voltage ≤ 1000 V rms		I-IV I-III	I-IV I-IV I-III	I-IV I-IV I-III I-III	I-IV I-IV I-IV I-III	
Climatic Classification		55/100/21	55/100/21	55/100/21	55/100/21	
Pollution Degree (DIN VDE 0110/1.89)		2	2	2	2	
Maximum Working Insulation Voltage	V_{IORM}	560	630	891	1414	V_{peak}
Input to Output Test Voltage, Method b* $V_{IORM} \times 1.875 = V_{PR}$, 100% Production Test with $t_m =$ 1 sec, Partial Discharge < 5 pC	V_{PR}	1050	1181	1670	2652	V_{peak}
Input to Output Test Voltage, Method a* $V_{IORM} \times 1.5 = V_{PR}$, Type and Sample Test, $t_m = 60$ sec, Partial Discharge < 5 pC	V_{PR}	840	945	1336	2121	V_{peak}
Highest Allowable Overvoltage* (Transient Overvoltage, $t_{ini} = 10$ sec)	V_{IOTM}	4000	6000	6000	8000	V_{peak}
Safety Limiting Values – maximum values allowed in the event of a fail- ure, also see Thermal Derating curve.						
Case Temperature	T_S	150	175	175	150	$^{\circ}C$
Input Current	$I_{S INPUT}$	150	230	400	400	mA
Output Power	$P_{S OUTPUT}$	600	600	600	700	mW
Insulation Resistance at T_S , $V_{IO} = 500$ V	R_S	$\geq 10^9$	$\geq 10^9$	$\geq 10^9$	$\geq 10^9$	Ω

*Refer to the optocoupler section of the Designer's Catalog, under regulatory information (IEC/EN/DIN EN 60747-5-2) for a detailed description of Method a and Method b partial discharge test profiles.

Notes:

These optocouplers are suitable for "safe electrical isolation" only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuits.

Insulation Characteristics are per IEC/EN/DIN EN 60747-5-2.

Surface mount classification is Class A in accordance with CECC 00802.

Absolute Maximum Ratings

Parameter	Symbol	Min.	Max.	Units
Storage Temperature	T_S	-55	125	°C
Operating Temperature	T_A	-40	100	°C
Average Input Current ^[1]	$I_{F(avg)}$		25	mA
Peak Input Current ^[2] (50% duty cycle, ≤ 1 ms pulse width)	$I_{F(peak)}$		50	mA
Peak Transient Input Current (<1 μ s pulse width, 300 pps)	$I_{F(tran)}$		1.0	A
Reverse Input Voltage (Pin 3-2)	HCPL-4506, HCPL-0466		5	Volts
	HCPL-J456, HCNW4506		3	
Average Output Current (Pin 6)	$I_{O(avg)}$		15	mA
Resistor Voltage (Pin 7)	V_7	-0.5	V_{CC}	Volts
Output Voltage (Pin 6-5)	V_O	-0.5	30	Volts
Supply Voltage (Pin 8-5)	V_{CC}	-0.5	30	Volts
Output Power Dissipation ^[3]	P_O		100	mW
Total Power Dissipation ^[4]	P_T		145	mW
Lead Solder Temperature (HCPL-4506, HCPL-J456)	260°C for 10 s, 1.6 mm below seating plane			
Lead Solder Temperature (HCNW4506)	260°C for 10 s (up to seating plane)			
Infrared and Vapor Phase Reflow Temperature (HCPL-0466 and Option 300)	See Package Outline Drawings Section			

Recommended Operating Conditions

Parameter	Symbol	Min.	Max.	Units
Power Supply Voltage	V_{CC}	4.5	30	Volts
Output Voltage	V_O	0	30	Volts
Input Current (ON)	$I_{F(on)}$	10	20	mA
Input Voltage (OFF)	$V_{F(off)}$ *	-5	0.8	V
Operating Temperature	T_A	-40	100	°C

*Recommended $V_{F(OFF)}$ = -3 V to 0.8 V for HCPL-J456, HCNW4506.

Electrical Specifications

Over recommended operating conditions unless otherwise specified:

$T_A = -40^\circ\text{C}$ to $+100^\circ\text{C}$, $V_{CC} = +4.5\text{ V}$ to 30 V , $I_{F(\text{on})} = 10\text{ mA}$ to 20 mA , $V_{F(\text{off})} = -5\text{ V}$ to 0.8 V^\dagger

Parameter	Symbol	Device	Min.	Typ.*	Max.	Units	Test Conditions	Fig.	Note
Current Transfer Ratio	CTR		44	90		%	$I_F = 10\text{ mA}$, $V_O = 0.6\text{ V}$		5
Low Level Output Current	I_{OL}		4.4	9.0		mA	$I_F = 10\text{ mA}$, $V_O = 0.6\text{ V}$	1, 2	
Low Level Output Voltage	V_{OL}			0.3	0.6	V	$I_O = 2.4\text{ mA}$		
Input Threshold Current	I_{TH}	HCPL-4506 HCPL-0466 HCNW4506		1.5	5	mA	$V_O = 0.8\text{ V}$, $I_O = 0.75\text{ mA}$	1	16
		HCPL-J456		0.6					
High Level Output Current	I_{OH}			5	50	μA	$V_F = 0.8\text{ V}$	3	
High Level Supply Current	I_{CCH}			0.6	1.3	mA	$V_F = 0.8\text{ V}$, $V_O = \text{Open}$		16
Low Level Supply Current	I_{CCL}			0.6	1.3	mA	$I_F = 10\text{ mA}$, $V_O = \text{Open}$		16
Input Forward Voltage	V_F	HCPL-4506 HCPL-0466		1.5	1.8	V	$I_F = 10\text{ mA}$	4	
		HCPL-J456	1.2	1.6	1.95				
		HCNW4506		1.6	1.85				
Temperature Coefficient of Forward Voltage	$\Delta V_F/\Delta T_A$	HCPL-4506 HCPL-0466		-1.6		mV/ $^\circ\text{C}$	$I_F = 10\text{ mA}$		
		HCPL-J456 HCNW4506		-1.3					
Input Reverse Breakdown Voltage	BV_R	HCPL-4506 HCPL-0466	5			V	$I_R = 10\text{ }\mu\text{A}$		
		HCPL-J456 HCNW4506	3				$I_R = 100\text{ }\mu\text{A}$		
Input Capacitance	C_{IN}	HCPL-4506 HCPL-0466		60		pF	$f = 1\text{ MHz}$, $V_F = 0\text{ V}$		
		HCPL-J456 HCNW4506		72					
Internal Pull-up Resistor	R_L		14	20	25	k Ω	$T_A = 25^\circ\text{C}$		12, 13
Internal Pull-up Resistor Temperature Coefficient	$\Delta R_L/\Delta T_A$			0.014		k $\Omega/^\circ\text{C}$			

*All typical values at 25°C , $V_{CC} = 15\text{ V}$.

$^\dagger V_{F(\text{off})} = -3\text{ V}$ to 0.8 V for HCPL-J456, HCNW4506.

Switching Specifications ($R_L = 20\text{ k}\Omega$ External)

Over recommended operating conditions unless otherwise specified:

$T_A = -40^\circ\text{C}$ to $+100^\circ\text{C}$, $V_{CC} = +4.5\text{ V}$ to 30 V , $I_{F(on)} = 10\text{ mA}$ to 20 mA , $V_{F(off)} = -5\text{ V}$ to 0.8 V^\dagger

Parameter	Symbol	Min.	Typ.*	Max.	Units	Test Conditions	Fig.	Note
Propagation Delay Time to Logic Low at Output	T_{PHL}	30	200	400	ns	$C_L = 100\text{ pF}$ $I_{F(on)} = 10\text{ mA}$, $V_{F(off)} = 0.8\text{ V}$, $V_{CC} = 15.0\text{ V}$,	6, 8, 10- 13	11, 14, 16
			100	480				
Propagation Delay Time to High Output Level	T_{PLH}	270	400	550	ns	$C_L = 100\text{ pF}$ $V_{THLH} = 2.0\text{ V}$, $V_{THHL} = 1.5\text{ V}$		
			130					
Pulse Width Distortion	PWD		200	450	ns	$C_L = 100\text{ pF}$		20
Propagation Delay Difference Between Any 2 Parts	$t_{PLH} - t_{PHL}$	-150	200	450	ns			17
Output High Level Common Mode Transient Immunity	$ CM_H $	15	30		kV/ μs	$I_F = 0\text{ mA}$, $V_O > 3.0\text{ V}$	7	18
Output Low Level Common Mode Transient Immunity	$ CM_L $	15	30		kV/ μs	$I_F = 10\text{ mA}$ $V_O < 1.0\text{ V}$		19

Switching Specifications ($R_L = \text{Internal Pull-up}$)

Over recommended operating conditions unless otherwise specified:

$T_A = -40^\circ\text{C}$ to $+100^\circ\text{C}$, $V_{CC} = +4.5\text{ V}$ to 30 V , $I_{F(on)} = 10\text{ mA}$ to 20 mA , $V_{F(off)} = -5\text{ V}$ to 0.8 V^\dagger

Parameter	Symbol	Min.	Typ.*	Max.	Units	Test Conditions	Fig.	Note
Propagation Delay Time to Logic Low at Output	t_{PHL}	20	200	400	ns	$I_{F(on)} = 10\text{ mA}$, $V_{F(off)} = 0.8\text{ V}$, $V_{CC} = 15.0\text{ V}$, $C_L = 100\text{ pF}$, $V_{THLH} = 2.0\text{ V}$, $V_{THHL} = 1.5\text{ V}$	6, 9	11-14, 16
			485					
Propagation Delay Time to High Output Level	t_{PLH}	220	450	650	ns			
Pulse Width Distortion	PWD		250	500	ns			20
Propagation Delay Difference Between Any 2 Parts	$t_{PLH} - t_{PHL}$	-150	250	500	ns			17
Output High Level Common Mode Transient Immunity	$ CM_H $		30		kV/ μs	$I_F = 0\text{ mA}$, $V_O > 3.0\text{ V}$	7	18
Output Low Level Common Mode Transient Immunity	$ CM_L $		30		kV/ μs	$I_F = 16\text{ mA}$, $V_O < 1.0\text{ V}$		19
Power Supply Rejection	PSR		1.0		V_{p-p}	Square Wave, t_{RISE} , t_{FALL} > 5 ns, no bypass capacitors		16

*All typical values at 25°C , $V_{CC} = 15\text{ V}$.

$^\dagger V_{F(off)} = -3\text{ V}$ to 0.8 V for HCPL-J456, HCNW4506.

Package Characteristics

Over recommended temperature ($T_A = -40^{\circ}\text{C}$ to 100°C) unless otherwise specified.

Parameter	Sym.	Device	Min.	Typ.*	Max.	Units	Test Conditions	Fig.	Note
Input-Output Momentary Withstand Voltage†	V_{ISO}	HCPL-4506	3750			V rms	RH < 50% t = 1 min. $T_A = 25^{\circ}\text{C}$		6,7,10
		HCPL-0466							
		HCPL-J456	3750						6,8,10
		HCPL-4506 Option020	5000						6,9, 15
HCNW4506	5000				6,9,10				
Resistance (Input-Output)	R_{I-O}	HCPL-4506		10^{12}		Ω	$V_{I-O} = 500\text{ Vdc}$		6
		HCPL-J456							
		HCPL-0466							
HCNW4506	10^{12}	10^{13}							
Capacitance (Input-Output)	C_{I-O}	HCPL-4506		0.6		pF	f = 1 MHz		6
		HCPL-0466							
		HCPL-J456		0.8					
HCNW4506		0.5							

*All typical values at 25°C , $V_{CC} = 15\text{ V}$.

†The Input-Output Momentary Withstand Voltage is a dielectric voltage rating that should not be interpreted as an input-output continuous voltage rating. For the continuous voltage rating refer to the IEC/EN/DIN EN 60747-5-2 Insulation Related Characteristics Table (if applicable), your equipment level safety specification or Avago Application Note 1074 entitled "Optocoupler Input-Output Endurance Voltage," publication number 5963-2203E.

Notes:

- Derate linearly above 90°C free-air temperature at a rate of $0.8\text{ mA}/^{\circ}\text{C}$.
- Derate linearly above 90°C free-air temperature at a rate of $1.6\text{ mA}/^{\circ}\text{C}$.
- Derate linearly above 90°C free-air temperature at a rate of $3.0\text{ mW}/^{\circ}\text{C}$.
- Derate linearly above 90°C free-air temperature at a rate of $4.2\text{ mW}/^{\circ}\text{C}$.
- CURRENT TRANSFER RATIO in percent is defined as the ratio of output collector current (I_O) to the forward LED input current (I_F) times 100.
- Device considered a two-terminal device: Pins 1, 2, 3, and 4 shorted together and Pins 5, 6, 7, and 8 shorted together.
- In accordance with UL 1577, each optocoupler is proof tested by applying an insulation test voltage $\geq 4500\text{ V rms}$ for 1 second (leakage detection current limit, $I_{I-O} \leq 5\text{ }\mu\text{A}$).
- In accordance with UL 1577, each optocoupler is proof tested by applying an insulation test voltage $\geq 4500\text{ V rms}$ for 1 second (leakage detection current limit, $I_{I-O} \leq 5\text{ }\mu\text{A}$).
- In accordance with UL 1577, each optocoupler is proof tested by applying an insulation test voltage $\geq 6000\text{ V rms}$ for 1 second (leakage detection current limit, $I_{I-O} \leq 5\text{ }\mu\text{A}$).
- This test is performed before the 100% Production test shown in the IEC/EN/DIN EN 60747-5-2 Insulation Related Characteristics Table, if applicable.
- Pulse: f = 20 kHz, Duty Cycle = 10%.
- The internal 20 k Ω resistor can be used by shorting pins 6 and 7 together.
- Due to tolerance of the internal resistor, and since propagation delay is dependent on the load resistor value, performance can be improved by using an external 20 k Ω 1% load resistor. For more information on how propagation delay varies with load resistance, see Figure 8.
- The $R_L = 20\text{ k}\Omega$, $C_L = 100\text{ pF}$ load represents a typical IPM (Intelligent Power Module) load.
- See Option 020 data sheet for more information.
- Use of a 0.1 μF bypass capacitor connected between pins 5 and 8 can improve performance by filtering power supply line noise.
- The difference between t_{PLH} and t_{PHL} between any two devices under the same test condition. (See IPM Dead Time and Propagation Delay Specifications section.)
- Common mode transient immunity in a Logic High level is the maximum tolerable dV_{CM}/dt of the common mode pulse, V_{CM} , to assure that the output will remain in a Logic High state (i.e., $V_O > 3.0\text{ V}$).
- Common mode transient immunity in a Logic Low level is the maximum tolerable dV_{CM}/dt of the common mode pulse, V_{CM} , to assure that the output will remain in a Logic Low state (i.e., $V_O < 1.0\text{ V}$).
- Pulse Width Distortion (PWD) is defined as $|t_{PHL} - t_{PLH}|$ for any given device.



Figure 1. Typical transfer characteristics.



Figure 2. Normalized output current vs. temperature.



Figure 3. High level output current vs. temperature.



Figure 4. HCPL-4506 and HCPL-0466 input current vs. forward voltage.



Figure 5. HCPL-J456 and HCNW4506 input current vs. forward voltage.



Figure 6. Propagation delay test circuit.



Figure 7. CMR test circuit. Typical CMR waveform.



Figure 8. Propagation delay with external 20 kΩ RL vs. temperature.



Figure 9. Propagation delay with internal 20 kΩ RL vs. temperature.



Figure 10. Propagation delay vs. load resistance.



Figure 11. Propagation delay vs. load capacitance.



Figure 12. Propagation delay vs. supply voltage.



Figure 13. Propagation delay vs. input current.



Figure 14. Thermal derating curve, dependence of safety limiting value with case temperature per IEC/EN/DIN EN 60747-5-2.

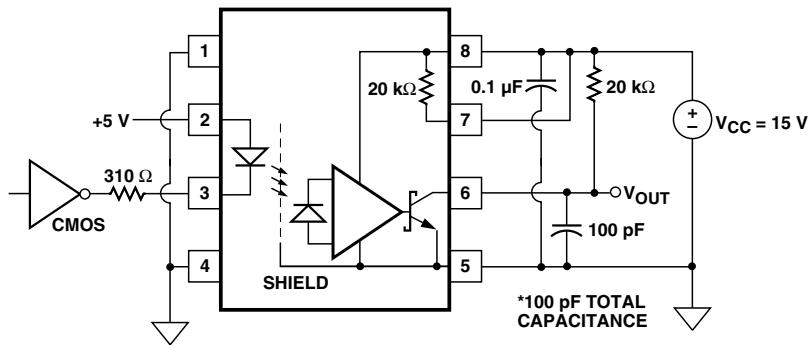


Figure 15. Recommended LED drive circuit.



Figure 16. Optocoupler input to output capacitance model for unshielded optocouplers.

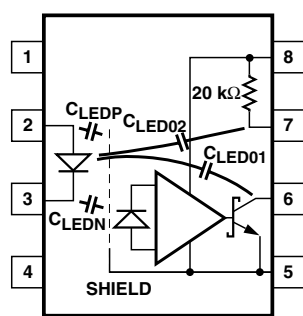


Figure 17. Optocoupler input to output capacitance model for shielded optocouplers.

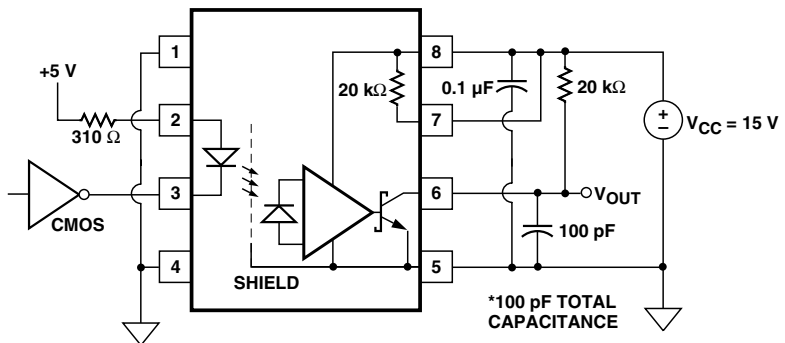


Figure 18. LED drive circuit with resistor connected to LED anode (not recommended).



Figure 19. AC equivalent circuit for Figure 18 during common mode transients.



Figure 20. AC equivalent circuit for Figure 15 during common mode transients.



Figure 21. Not recommended open collector LED drive circuit.



Figure 22. AC Equivalent circuit for Figure 21 during common mode transients.



Figure 23. Recommended LED drive circuit for ultra high CMR.



Figure 24. Typical application circuit.



*PDD = PROPAGATION DELAY DIFFERENCE

NOTE: THE PROPAGATION DELAYS USED TO CALCULATE PDD ARE TAKEN AT EQUAL TEMPERATURES.

Figure 25. Minimum LED skew for zero dead time.



*PDD = PROPAGATION DELAY DIFFERENCE

NOTE: THE PROPAGATION DELAYS USED TO CALCULATE THE MAXIMUM DEAD TIME ARE TAKEN AT EQUAL TEMPERATURES.

Figure 26. Waveforms for dead time calculation.

LED Drive Circuit Considerations for Ultra High CMR Performance

Without a detector shield, the dominant cause of optocoupler CMR failure is capacitive coupling from the input side of the optocoupler, through the package, to the detector IC as shown in Figure 16. The HCPL-4506 series improve CMR performance by using a detector IC with an optically transparent Faraday shield, which diverts the capacitively coupled current away from the sensitive IC circuitry. However, this shield does not eliminate the capacitive coupling between the LED and the optocoupler output pins and output ground as shown in Figure 17. This capacitive coupling causes perturbations in the LED current during common mode transients and becomes the major source of CMR failures for a shielded optocoupler. The main design objective of a high CMR LED drive circuit becomes keeping the LED in the proper state (on or off) during common mode transients. For example, the recommended application circuit (Figure 15), can achieve $15\text{ kV}/\mu\text{s}$ CMR while minimizing component complexity. Note that a CMOS gate is recommended in Figure 15 to keep the LED off when the gate is in the high state.

Another cause of CMR failure for a shielded optocoupler is direct coupling to the optocoupler output pins through C_{LEDO1} and C_{LEDO2} in Figure 17. Many factors influence the effect and magnitude of the direct coupling including: the use of an internal or external output pull-up resistor, the position of the LED current setting resistor, the connection of the unused input package pins, and the value of the capacitor at the optocoupler output (C_L).

Techniques to keep the LED in the proper state and minimize the effect of the direct coupling are discussed in the next two sections.

CMR with the LED On (CMR_L)

A high CMR LED drive circuit must keep the LED on during common mode transients. This is achieved by overdriving the LED current beyond the input threshold so that it is not pulled below the threshold during a transient. The recommended minimum LED current of 10 mA provides adequate margin over the maximum I_{TH} of 5.0 mA (see Figure 1) to achieve $15\text{ kV}/\mu\text{s}$ CMR. Capacitive coupling is higher when the internal load resistor is used (due to C_{LEDO2}) and an $I_F = 16\text{ mA}$ is required to obtain $10\text{ kV}/\mu\text{s}$ CMR.

The placement of the LED current setting resistor effects the ability of the drive circuit to keep the LED on during transients and interacts with the direct coupling to the optocoupler output. For example, the LED resistor in Figure 18 is connected to the anode. Figure 19 shows the AC equivalent circuit for Figure 18 during common mode transients. During a $+dV_{cm}/dt$ in Figure 19, the current available at the LED anode (I_{total}) is limited by the series resistor. The LED current (I_F) is reduced from its DC value by an amount equal to the current that flows through

C_{LEDP} and C_{LEDO1} . The situation is made worse because the current through C_{LEDO1} has the effect of trying to pull the output high (toward a CMR failure) at the same time the LED current is being reduced. For this reason, the recommended LED drive circuit (Figure 15) places the current setting resistor in series with the LED cathode. Figure 20 is the AC equivalent circuit for Figure 15 during common mode transients. In this case, the LED current is not reduced during a $+dV_{cm}/dt$ transient because the current flowing through the package capacitance is supplied by the power supply. During a $-dV_{cm}/dt$ transient, however, the LED current is reduced by the amount of current flowing through C_{LEDN} . But, better CMR performance is achieved since the current flowing in C_{LEDO1} during a negative transient acts to keep the output low.

Coupling to the LED and output pins is also affected by the connection of pins 1 and 4. If CMR is limited by perturbations in the LED on current, as it is for the recommended drive circuit (Figure 15), pins 1 and 4 should be connected to the input circuit common. However, if CMR performance is limited by direct coupling to the output when the LED is off, pins 1 and 4 should be left unconnected.

CMR with the LED Off (CMR_H)

A high CMR LED drive circuit must keep the LED off ($V_F \leq V_{F(OFF)}$) during common mode transients. For example, during a $+dV_{cm}/dt$ transient in Figure 20, the current flowing through C_{LEDN} is supplied by the parallel combination of the LED and series resistor. As long as the voltage developed across the resistor is less than $V_{F(OFF)}$ the LED will remain off and no common mode failure will occur. Even if the LED momentarily turns on, the 100 pF capacitor from pins 6-5 will keep the output from dipping below the threshold. The recommended LED drive circuit (Figure 15) provides about 10V of margin between the lowest optocoupler output voltage and a 3V IPM threshold during a $15\text{ kV}/\mu\text{s}$ transient with $V_{CM} = 1500\text{ V}$. Additional margin can be obtained by adding a diode in parallel with the resistor, as shown by the dashed line connection in Figure 20, to clamp the voltage across the LED below $V_{F(OFF)}$.

Since the open collector drive circuit, shown in Figure 21, cannot keep the LED off during a $+dV_{cm}/dt$ transient, it is not desirable for applications requiring ultra high CMR_H performance. Figure 22 is the AC equivalent circuit for Figure 21 during common mode transients. Essentially all the current flowing through C_{LEDN} during a $+dV_{cm}/dt$ transient must be supplied by the LED. CMR_H failures can occur at dV/dt rates where the current through the LED and C_{LEDN} exceeds the input threshold. Figure 23 is an alternative drive circuit which does achieve ultra high CMR performance by shunting the LED in the off state.